# **Schottky Power Rectifier**

## **Surface Mount Power Package**

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system.

#### **Features**

- Very Low Forward Voltage Drop (0.395 Volts Max @ 1.0 A, T<sub>I</sub> = 25°C)
- Small Compact Surface Mountable Package with J-Bend Leads
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Stress Protection
- ESD Ratings:
  - ◆ Human Body Model = 3B (> 16000 V)
  - ♦ Machine Model = C (> 400 V)
- AEC-Q101 Qualified and PPAP Capable
- SBRS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb–Free\*

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 100 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Cathode Polarity Band



## ON Semiconductor®

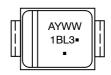
http://onsemi.com

## SCHOTTKY BARRIER RECTIFIER 1.0 AMPERE 30 VOLTS



SMB CASE 403A

#### **MARKING DIAGRAM**



1BL3 = Specific Device Code
A = Assembly Location
Y = Year

WW = Work Week
■ Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRS130LT3G	SMB (Pb-Free)	2,500 / Tape & Reel
SBRS8130LT3G	SMB (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30	V	
Average Rectified Forward Current $T_L = 120^{\circ}C$ $T_L = 110^{\circ}C$	I <sub>F(AV)</sub>	1.0 2.0	А	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	40	Α	
Operating Junction Temperature	TJ	-65 to +125	°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead	$\Psi_{\sf JL}$	12	°C/W
Thermal Resistance, Junction-to-Ambient (T <sub>A</sub> = 25°C, Min Pad, 1 oz copper) Junction-to-Ambient (T <sub>A</sub> = 25°C, 1" Pad, 1 oz copper)	$R_{ hetaJA}$	228.8 71.3	°C/W

### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) $(i_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C})$ $(i_F = 2.0 \text{ A}, T_J = 25^{\circ}\text{C})$	V <sub>F</sub>	0.395 0.445	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 25^{\circ}C$ ) (Rated dc Voltage, $T_J = 100^{\circ}C$ )	I <sub>R</sub>	1.0 10	mA

<sup>1.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

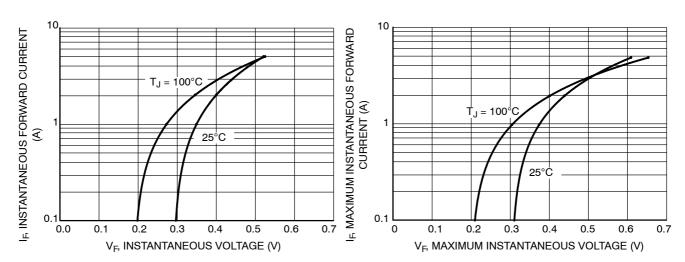
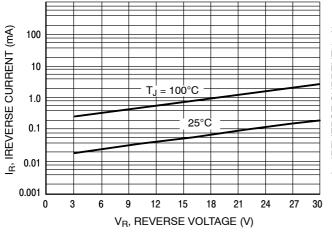


Figure 1. Typical Forward Voltage

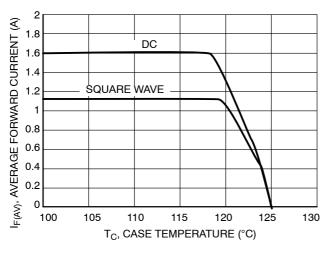
Figure 2. Maximum Forward Voltage



IR, IREVERSE CURRENT (mA) 100 10 T<sub>J</sub> = 100°C 1.0 25°C 0.1 0.01 0.001 3 12 15 24 27 0 18 V<sub>R</sub>, REVERSE VOLTAGE (V)

Figure 3. Typical Reverse Leakage Current

Figure 4. Typical Maximum Reverse Leakage Curent



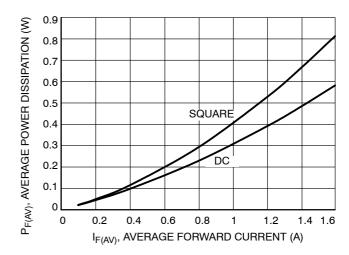


Figure 5. Current Derating (Case)

Figure 6. Typical Power Dissipation

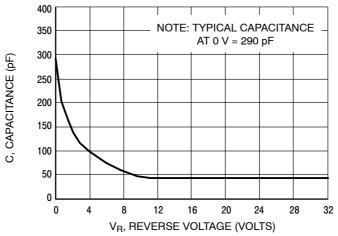


Figure 7. Typical Capacitance

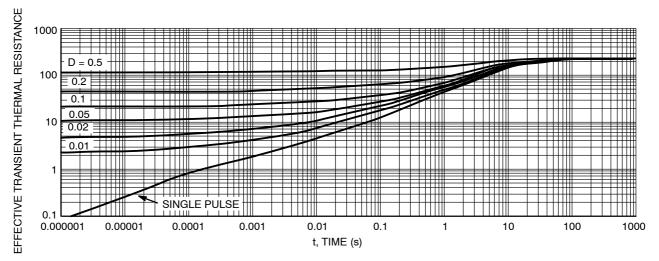


Figure 8. Thermal Response, Min Pad

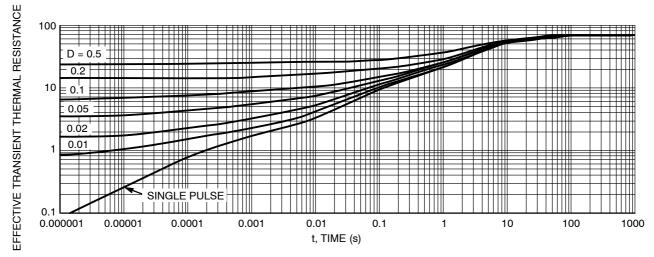


Figure 9. Thermal Response, 1 Inch Pad

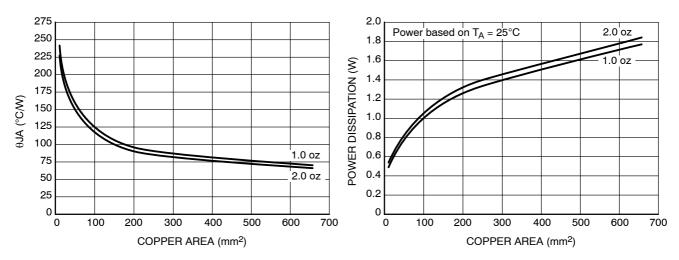
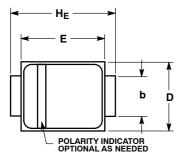


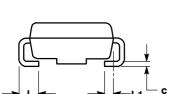
Figure 10. Thermal Resistance vs. Copper Area

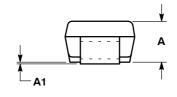
Figure 11. Power Dissipation vs. Copper Area

#### PACKAGE DIMENSIONS

#### **SMB** CASE 403A-03 **ISSUE H**





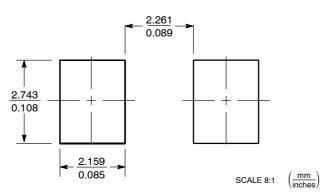


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
- D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.90	2.20	2.28	0.075	0.087	0.090
A1	0.05	0.10	0.19	0.002	0.004	0.007
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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